# Design of metal-ceramic interfaces for high temperature applications



Maria Luigia Muolo, Fabrizio Valenza, Sofia Gambaro, Gabriele Cacciamani<sup>#</sup>, Alberto Passerone

e-mail: marialuigia.muolo@ge.icmate.cnr.it

National Research Council - Institute of Condensed Matter Chemistry and Technologies for Energy, CNR-ICMATE, Genova, Via De Marini 6, 16149 <sup>#</sup> University of Genova – Department of Chemistry and Industrial Chemistry, DCCI, Genova, Via Dodecaneso 31, 16146

A combined experimental/thermodynamic approach is used. **<u>Phase diagrams</u>** obtained by the <u>CALPHAD</u> method show the equilibria between the metallic phase and the ceramic substrates. Even if the systems are studied under dynamic conditions, a comparison with phase equilibrium calculations is a useful way to understand high temperature interactions and phase transformations.



In *casting processes*, interactions between liquid superalloys (Ni-, Co- based) and ceramic mould materials must be studied in order to select the most proper materials combination and to avoid wetting and defects.

## CMSX 486 (Ni-based, with 5.7 at% of Al and 0.4 at% of Hf)

Interactions with mullite-based material (3Al<sub>2</sub>O<sub>3</sub>·2SiO<sub>2</sub>) – T = 1500°C



Wetting of ZrB, by Ni-B alloys Interfacial microstructures of cross-sectioned wetting samples in relation to phase diagram

NiB 50



Determination of the cooling path of the liquid phase

to optimize wetting of SiC by AlTi brazing alloys

Alter Alter



Dissolution of the ceramic substrate



Al-C-Si-Ti system

WD = 12.8 mm High Vacuum

### B-Ni-Zr isothermal section at 1500°C

 $Al_2O_3$  layer ( $\approx 2 \mu m$ ) and inclusions of HfO<sub>2</sub>

S/L interface

### Interactions with yttria-based material – T = 1500°C

**S/L interface:** small inclusions of ARIAN OR OR SEES



 $Y_2O_3$  based mould material are more inert than mullite based materials

Wettability

CALLAR CON MALAR tendency of a liquid to contact a solid surface. It is measured in terms of **contact angle** and interfacial energies

θ < 90 /

Wetting,  $\theta < 90^{\circ}$ 

Le to zo angle in interfacial  $\overset{\Upsilon_{sv}}{\longleftarrow}$ tensions between the three phases



θ > 90

Non wetting,  $\theta > 90^{\circ}$ 

 $\Upsilon_{sv} = \Upsilon_{LS} + \Upsilon_{LV} \cos \theta$  $\Upsilon_{ii}$ : interfacial tension  $\theta$  : contact angle

Liquid based joining processes (e.g. brazing, transient liquid phase bonding, soldering) rely on *capillarity* to distribute the liquid alloy along the adjoining interfaces

Temperature [°C]

Non-wetting both substrates

Al<sub>3</sub>Ti\_LT

substrates **Conditions for spontaneous liquid infiltration** 

Wetting both



## **Types of interfacial reactions at high temperatures**

- Formation of new compounds at the S/L interface





5 mm

Collaboration with Politecnico di Torino – DISAT (Prof. M. Ferraris, Prof. M. Salvo, Prof. V. Casalegno)

# YAG/Ti6Al4V joints with AgCuTi interlayers



## SiC – SiC joining using Al-Ti interlayers at 1200-1500°C





SiC-SiC joining by Ni-Si alloys and Mo interlayer at 1350°C



